

ECA MARKET ACTIVITY REPORTS & ANALYSIS PROGRAM
Reporting Form for
Total North American Sales and Bookings of Passive Networks MS-424M
(Thousands of Units/Dollars — Omit 000)

Participant Code _____

Month of _____ 2010

THICK FILM SALES

LINE	DESCRIPTION	<u>OEM</u>		<u>DISTRIBUTOR</u>		<u>EXPORT</u>		<u>TOTAL</u>	
		UNITS	DOLLARS	UNITS	DOLLARS	UNITS	DOLLARS	UNITS	DOLLARS
<u>DIPs</u>									
17	Resistor							0	0
18	Resistor/Capacitor							0	0
19	Total DIPs (sum of lines 17 & 18)	0	0	0	0	0	0	0	0
<u>SIPs</u>									
Resistor:									
20	Molded and Other Rectangular							0	0
21	Conformal							0	0
22	Resistor/Capacitor							0	0
23	Total SIPs (sum of lines 20, 21, & 22)	0	0	0	0	0	0	0	0
24	Total DIPs and SIPs (sum of lines 19 & 23)	0	0	0	0	0	0	0	0
<u>SURFACE-MOUNT DEVICES (SMDs)</u>									
(Other than Flat Pack)									
25	Leaded							0	0
26	Leadless (includes Chip Arrays)							0	0
27	Total SMDs (sum of lines 25 & 26)	0	0	0	0	0	0	0	0
<u>OTHER:</u>									
28	Flat-Pack							0	0
29	Unencapsulated Substrates							0	0
30	All Other							0	0
31	Total Other (sum of lines 28, 29, & 30)	0	0	0	0	0	0	0	0
<u>GRAND TOTAL</u>									
32	(sum of lines 24, 27, & 31)	0	0	0	0	0	0	0	0

Please upload your data at <https://secure.verisconsulting.com/eca/>
COMPLETED REPORT DUE ON OR BEFORE THE 20TH OF THE MONTH FOLLOWING THE REPORTING PERIOD.

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(Thousands of Units/Dollars — Omit 000)

Participant Code _____ 0

Month of _____ 0 _____ 0 2010

THICK FILM BOOKINGS

LINE	DESCRIPTION	<u>OEM</u>		<u>DISTRIBUTOR</u>		<u>EXPORT</u>		<u>TOTAL</u>	
		UNITS	DOLLARS	UNITS	DOLLARS	UNITS	DOLLARS	UNITS	DOLLARS
<u>DIPs</u>									
17	Resistor							0	0
18	Resistor/Capacitor							0	0
19	Total DIPs (sum of lines 17 & 18)	0	0	0	0	0	0	0	0
<u>SIPs</u>									
Resistor:									
20	Molded and Other Rectangular							0	0
21	Conformal							0	0
22	Resistor/Capacitor							0	0
23	Total SIPs (sum of lines 20, 21, & 22)	0	0	0	0	0	0	0	0
24	Total DIPs and SIPs (sum of lines 19 & 23)	0	0	0	0	0	0	0	0
<u>SURFACE-MOUNT DEVICES (SMDs)</u>									
(Other than Flat Pack)									
25	Leaded							0	0
26	Leadless (includes Chip Arrays)							0	0
27	Total SMDs (sum of lines 25 & 26)	0	0	0	0	0	0	0	0
<u>OTHER:</u>									
28	Flat-Pack							0	0
29	Unencapsulated Substrates							0	0
30	All Other							0	0
31	Total Other (sum of lines 28, 29, & 30)	0	0	0	0	0	0	0	0
<u>GRAND TOTAL</u>									
32	(sum of lines 24, 27, & 31)	0	0	0	0	0	0	0	0

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